

# WI-6500 Automatic Wafer Defect Inspection System

WI-6500 supports 25 wafer automatic-defect inspection systems. 25 6-inch wafers are carried into the system inspection wafer cassette by the shipping wafer cassette, the equipment closes the hatch. The vision system scans the number and position of the wafers in the cassette, and then the robot arm moves the wafer to the pre-aligner to align the wafers. The wafer then will be transferred to the front defect inspection module tray for rapid defect detection and extraction of defective images. After the inspection is completed, the system generates a defect map and simultaneously stores the result in the production line system database for operators and engineers to analyze the situation of defect of products.



| Defect detection system             |  |
|-------------------------------------|--|
| Detection type                      | Brightfield and darkfield  |
| Imaging type                        | Color / black and white  |
| Detection magnification             | 1.25X, 2.5X, 5X, 10X, 20X  |
| Defect review                       | Manual / automatic defect review   |
| Automatic classification of defects | Quickly and accurately classify and summarize defect areas, sizes, etc.                          |
| Measurement time                    | Each wafer ≤30min(6inch)   |
| Defect capture rate                 | Typical:99% @3 pixels size defects   |
| Defect loss rate                    | Typical:1%   |
| Recheck rate                        | Typical:1%   |
| Anti-vibration platform             | The device needs to be equipped with a vibration isolation platform to avoid external vibrations |
| Silicon wafer stage                 |  |
| Compatible wafer size               | 6 inch / 8 inch wafer  |
| Autofocus                           | The lens is equipped with a Z-axis motor for automatic focusing                                  |
| XY and rotary stage                 | XY-direction stage is required for inspection and rotation stage is required for calibration     |
| Automatic loading                   |  |
| Equipment loading                   | One wafer cassette at a time, at least 25 wafers one cassette                                    |
| Pre-calibration                     | Automatic pre-calibration before loading into wafer chuck  |
| Submodule                           | Automatic loading can be used as a sub-module, optional according to user's needs                |

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